5-V PECL/ECL 1:2 Fanout Buffer

FEATURES

- 1:2 PECL/ECL Fanout Buffer
- Operating Range
  - PECL: V_{CC} = 4.2 V to 5.7 V With V_{EE} = 0 V
  - NECL: V_{CC} = 0 V With V_{EE} = –4.2 V to –5.7 V
- 5-ps Skew Between Outputs
- Support for Clock Frequencies >2.5 GHz
- 265-ps Typical Propagation Delay
- Deterministic Output Value for Open Input Conditions
- Drop-In Compatible With MC10EL11, MC100EL11
- Built-In Input Pulldown Resistors
- Built-In Temperature Compensation

APPLICATIONS

- Data and Clock Transmission Over Backplane
- Signaling Level Conversion

DESCRIPTION

The SN65EL11 is a differential 1:2 PECL/ECL fanout buffer. The device includes circuitry to maintain a known logic level when inputs are in an open condition. The SN65EL11 is housed in an industry-standard SOIC-8 package and is also available in a TSSOP-8 package.

PINOUT ASSIGNMENT

D-8, DGK-8 Package
(Top View)

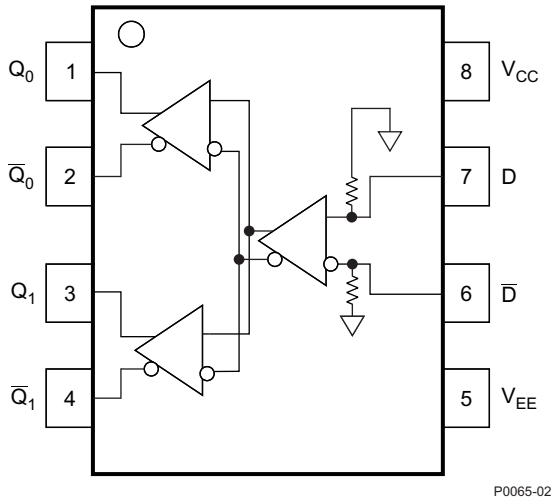

Table 1. Pin Description

PIN	FUNCTION
D, $\overline{D}$	PECL/ECL data inputs
Q_0, $\overline{Q}_0$, Q_1, $\overline{Q}_1$	PECL/ECL outputs
Vcc	Positive supply
V_{EE}	Negative supply

ORDERING INFORMATION(1)

PART NUMBER	PART MARKING	PACKAGE	LEAD FINISH
SN65EL11D	SN65EL11	SOIC	NiPdAu
SN65EL11DGK	SN65EL11	SOIC-TSSOP	NiPdAu

(1) Leaded device options not initially available; contact a sales representative for further details.

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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ABSOLUTE MAXIMUM RATINGS(1)

PARAMETER	CONDITIONS	VALUE	UNIT
Absolute PECL-mode supply voltage, V_{CC}	V_{EE} = 0 V	6	V
Absolute NECL-mode supply voltage, V_{EE}	V_{CC} = 0 V	–6	V
PECL-mode input voltage	V_{EE} = 0 V; $V_I \le V_{CC}$	6	V
NECL-mode input voltage	V_{CC} = 0 V; $V_I \ge V_{EE}$	–6	V
Output current	Continuous	50	mA
	Surge	100	mA
Operating temperature range		–40 to 85	°C
Storage temperature range		–65 to 150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

POWER DISSIPATION RATINGS

PACKAGE	CIRCUIT BOARD MODEL	POWER RATING T_A < 25°C (mW)	THERMAL RESISTANCE, JUNCTION-TO-AMBIENT, NO AIRFLOW	DERATING FACTOR T_A > 25°C (mW/°C)	POWER RATING T_A = 85°C (mW)
SOIC	Low-K	719	139	7	288
	High-K	840	119	8	336
SOIC-TSSOP	Low-K	469	213	5	188
	High-K	527	189	5	211

THERMAL CHARACTERISTICS

PARAMETER		PACKAGE	VALUE	UNIT
θ_{JB}	Junction-to-board thermal resistance	SOIC	79	°C/W
		SOIC-TSSOP	120	
θ_{JC}	Junction-to-case thermal resistance	SOIC	98	°C/W
		SOIC-TSSOP	74	

KEY ATTRIBUTES

CHARACTERISTICS	VALUE
Internal input pulldown resistor	75 kΩ
Moisture sensitivity level	Level 1
Flammability rating (oxygen index: 28 to 34)	UL 94 V-0 at 0.125 in
ESD-HBM	4 kV
ESD-machine model	200 V
Meets or exceeds JEDEC Spec EIA/JESD78 latchup test	

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PECL DC CHARACTERISTICS[1] (V_{CC} = 5 V; V_{EE} = 0 V)[2]

PARAMETER		–40°C			25°C			85°C			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
I_{CC}	Power-supply current		18	26		21	26		23	26	mA
V_{OH}	Output HIGH voltage[3]	3915		4120	3915	4000	4120	3915		4120	mV
V_{OL}	Output LOW voltage[3]	3170		3380	3170	3288	3380	3170		3380	mV
V_{IH}	Input HIGH voltage (single-ended)	3835		4120	3835		4120	3835		4120	mV
V_{IL}	Input LOW voltage (single-ended)	3190		3525	3190		3525	3190		3525	mV
V_{IHCMR}	Input HIGH voltage, common-mode range (differential)[4]	2.5		4.6	2.5		4.6	2.5		4.6	V
I_{IH}	Input HIGH current			150			150			150	µA
I_{IL}	Input LOW current	0.5			0.5			0.5			µA

(1) The device meets these specifications after thermal equilibrium has been established when mounted in a test socket or printed-circuit board with maintained transverse airflow greater than 500 lfpm (2.54 m/s). Electrical parameters are assured only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.
(2) Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.25 V / –0.5 V.
(3) Outputs are terminated through a 50-Ω resistor to V_{CC} – 2 V.
(4) V_{IHCMR} min varies 1:1 with V_{EE}; V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the more-positive side of the differential input signal. Normal operation is obtained if the HIGH level falls within the specified range and the peak-to-peak voltage lies between V_{PP} min and 1 V.

NECL DC CHARACTERISTICS[1] (V_{CC} = 0 V; V_{EE} = 5 V)[2]

PARAMETER		–40°C			25°C			85°C			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
I_{EE}	Power-supply current		19	26		21	26		23	26	mA
V_{OH}	Output HIGH voltage[3]	–1085		–880	–1025	–995	–880	–1025		–880	mV
V_{OL}	Output LOW voltage[3]	–1830		–1620	–1810	–1712	–1620	–1810		–1620	mV
V_{IH}	Input HIGH voltage (single-ended)	–1165		–880	–1165		–880	–1165		–880	mV
V_{IL}	Input LOW voltage (single-ended)	–1810		–1475	–1810		–1475	–1810		–1475	mV
V_{IHCMR}	Input HIGH voltage, common-mode range (differential)[4]	–2.5		–0.4	–2.5		–0.4	–2.5		–0.4	V
I_{IH}	Input HIGH current			150			150			150	µA
I_{IL}	Input LOW current	0.5			0.5			0.5			µA

(1) The device meets these specifications after thermal equilibrium has been established when mounted in a test socket or printed-circuit board with maintained transverse airflow greater than 500 lfpm (2.54 m/s). Electrical parameters are assured only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.
(2) Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.25 V / –0.5 V.
(3) Outputs are terminated through a 50-Ω resistor to V_{CC} – 2 V.
(4) V_{IHCMR} min varies 1:1 with V_{EE}; V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the more-positive side of the differential input signal. Normal operation is obtained if the HIGH level falls within the specified range and the peak-to-peak voltage lies between V_{PP} min and 1 V.

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AC CHARACTERISTICS[1] (V_{CC} = 5 V; V_{EE} = 0 V or V_{CC} = 0 V; V_{EE} = –5 V)[2]

PARAMETER		–40°C			25°C			85°C			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
f_{MAX}	Maximum switching frequency[3] (see Figure 6)		3.5			3.4			3.1		GHz
t_{PLH}/t_{PHL}	Propagation delay to output (see Figure 2)	200		300	200		300	200		300	ps
t_{SKEW}	Device skew[4] (see Figure 5)		7	15		7	15		7	15	ps
	Duty cycle skew[5]		5	15		5	15		5	15	
t_{JITTER}	Random clock jitter (RMS)		0.2			0.2			0.2		ps
V_{PP}	Input swing[6] (see Figure 3)	150		1000	150		1000	150		1000	mV
t_r/t_f	Q-output rise/fall times (20%–80%) (see Figure 4)	150		250	150		250	150		250	ps

(1) The device meets these specifications after thermal equilibrium has been established when mounted in a test socket or printed-circuit board with maintained transverse airflow greater than 500 lfpm (2.54 m/s). Electrical parameters are assured only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.
(2) Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.25 V / –0.5 V.
(3) Maximum switching frequency is measured at an output amplitude of 300 mVpp.
(4) Within-device skew defined as identical transitions on similar paths through a device.
(5) Duty cycle skew is the difference between a t_{PLH} and t_{PHL} propagation delay through a device.
(6) $V_{PP(min)}$ is the minimum input swing for which ac parameters are assured.

Typical Termination for Output Driver

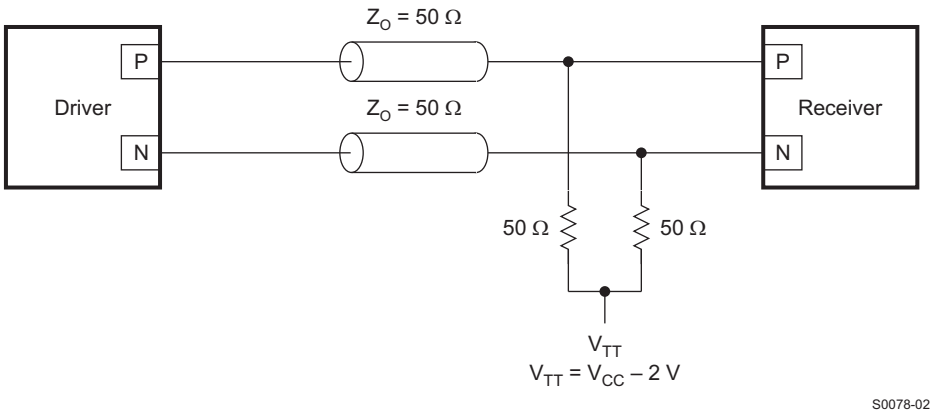

Figure 1. Typical Termination for Output Driver

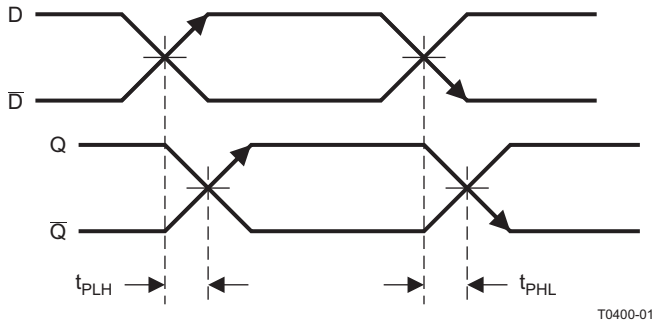

Figure 2. Propagation Delay

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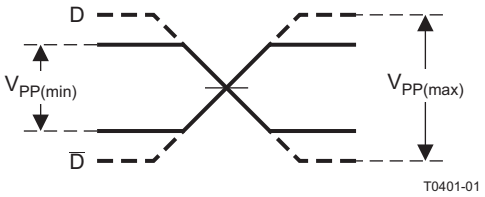

Figure 3. Input Voltage Swing

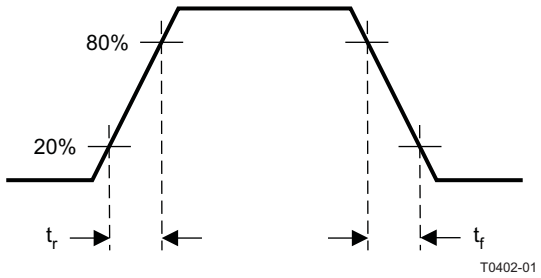

Figure 4. Output Rise and Fall Times

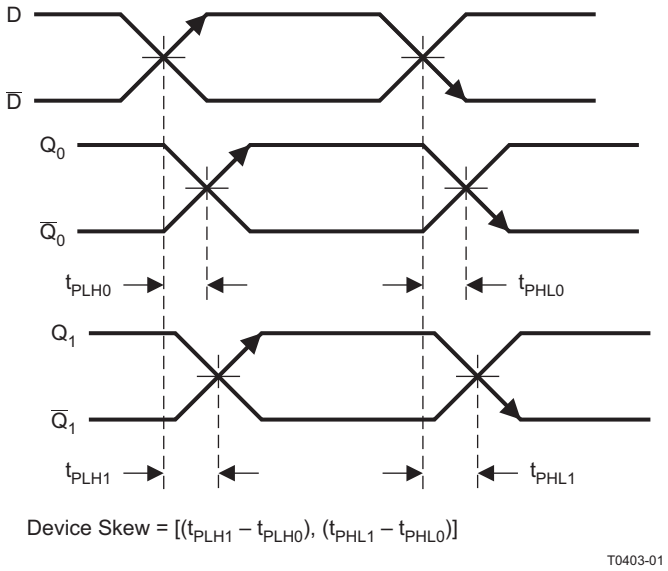

Figure 5. Device Skew

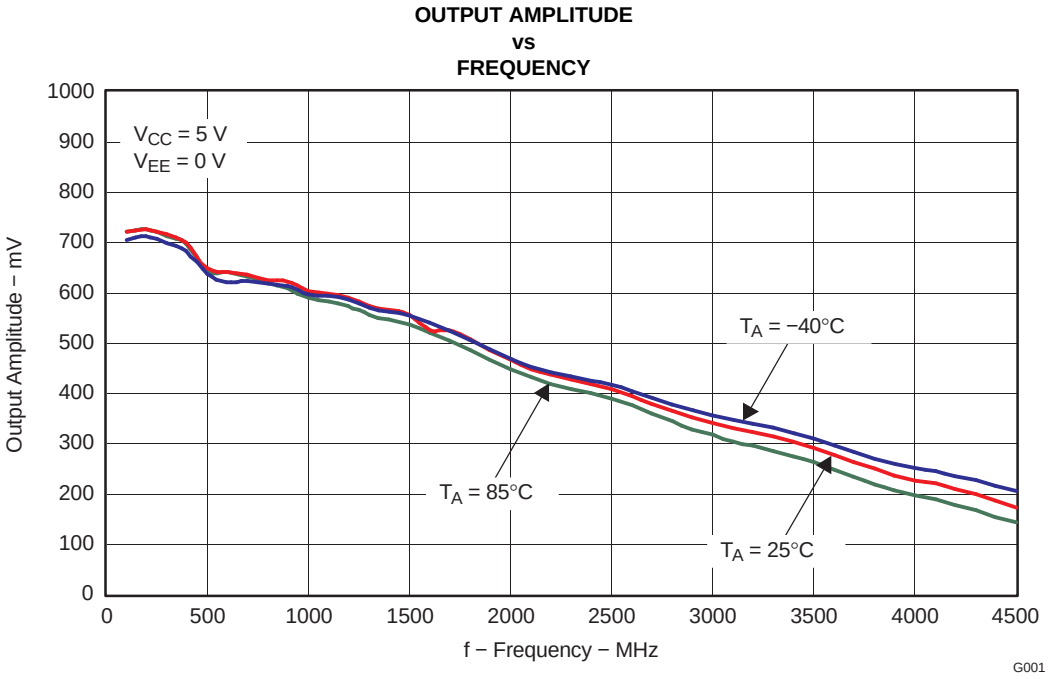

Figure 6.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
SN65EL11D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65EL11DGK	ACTIVE	MSOP	DGK	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65EL11DGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65EL11DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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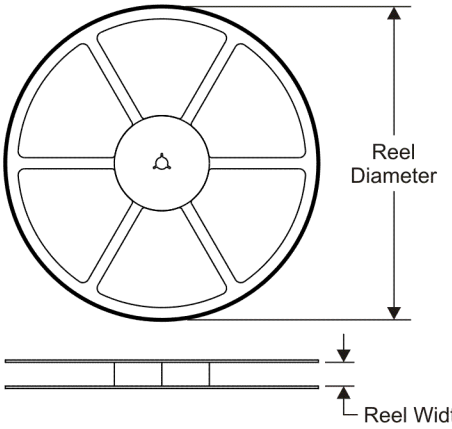
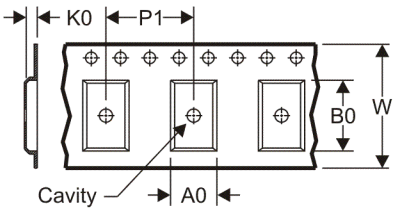
TAPE AND REEL INFORMATION

REEL DIMENSIONS

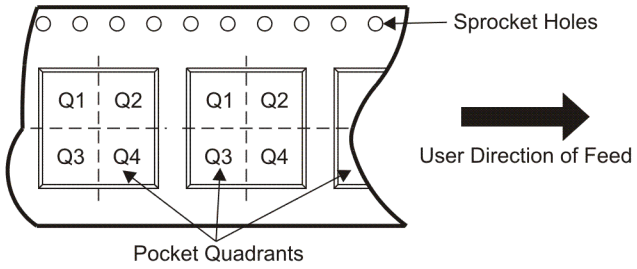


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

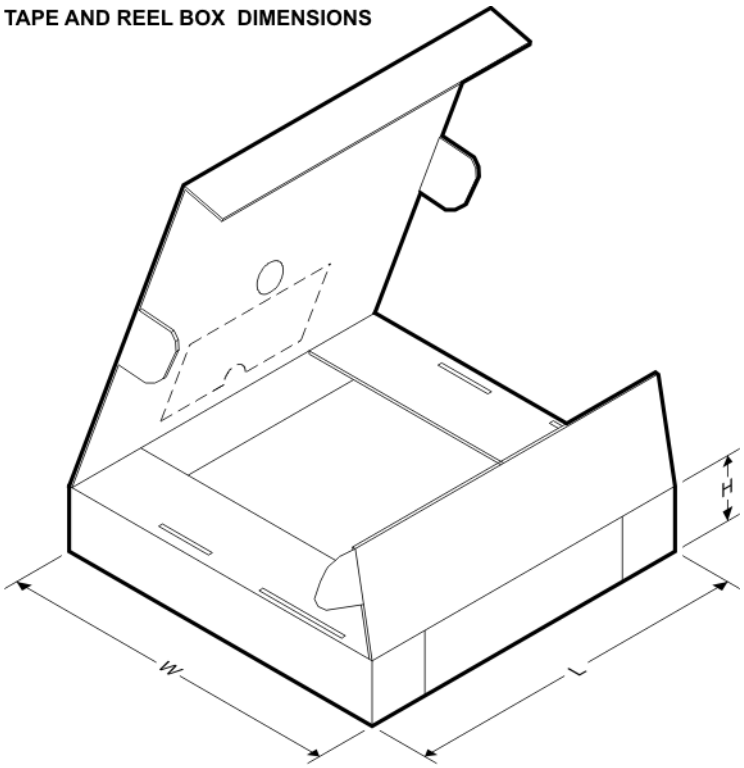
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65EL11DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

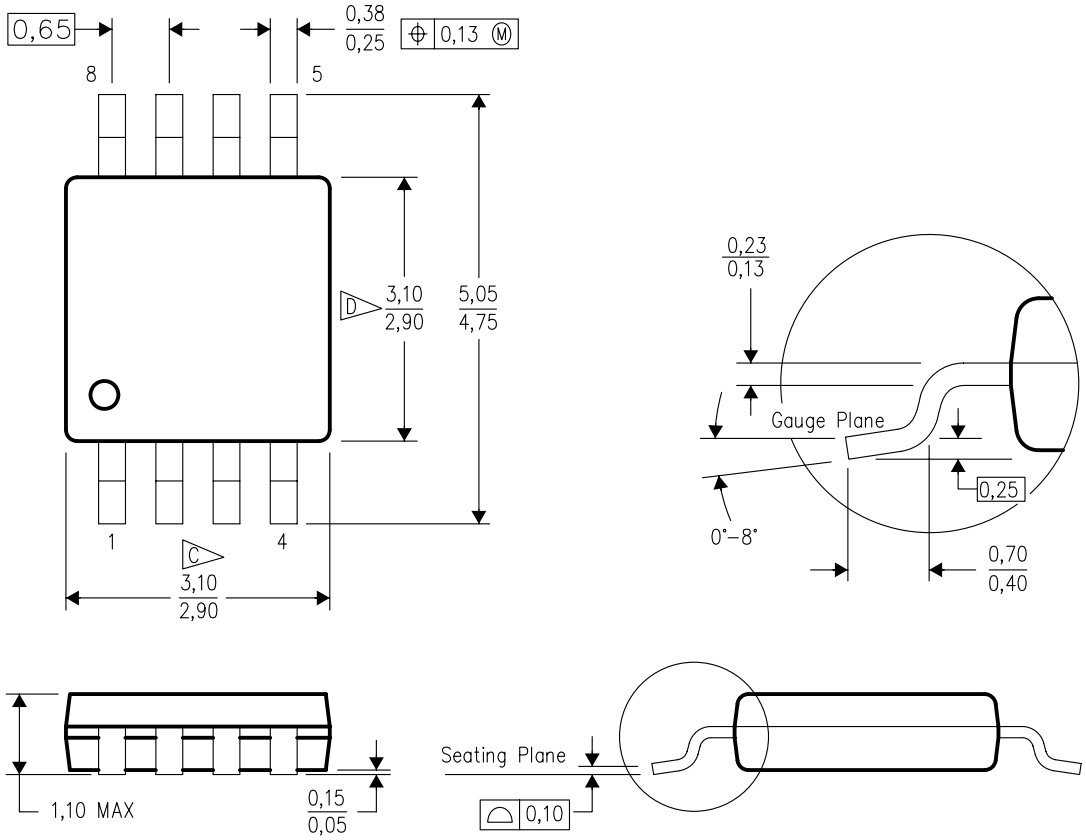
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65EL11DR	SOIC	D	8	2500	346.0	346.0	29.0

DGK (S–PDSO–G8) PLASTIC SMALL–OUTLINE PACKAGE



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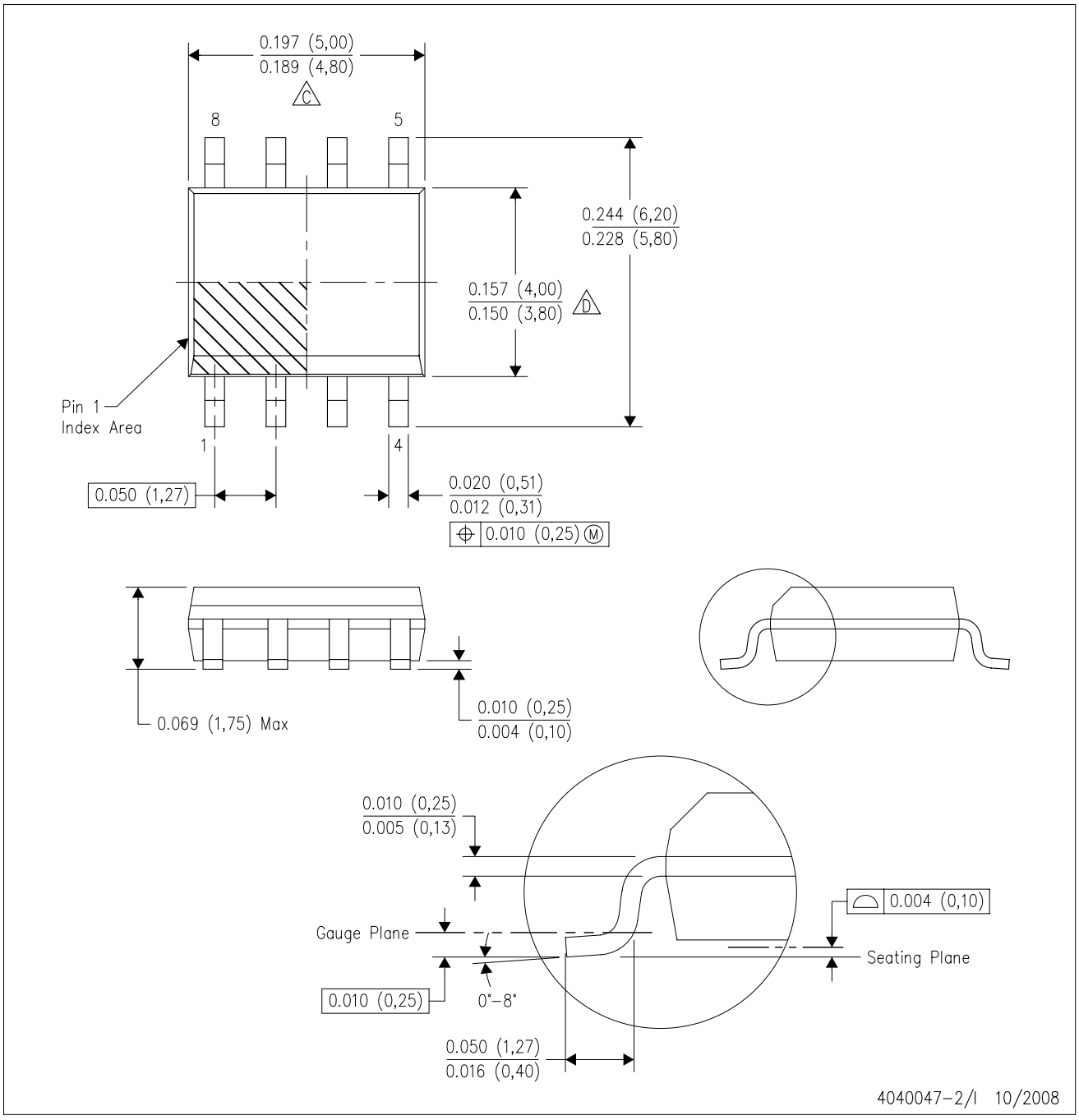
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
E. Falls within JEDEC MO–187 variation AA, except interlead flash.

D (R–PDSO–G8) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
E. Reference JEDEC MS–012 variation AA.

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